

## 60V Nch+Nch Power MOSFET

V <sub>DSS</sub>	60V
R <sub>DS(on)</sub> (Max.)	12.4mΩ
I <sub>D</sub>	±10.5A
P <sub>D</sub>	2.0W

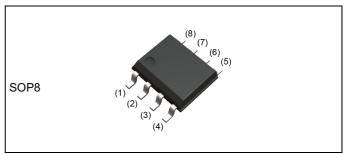
## Features

- 1) Low on resistance
- 2) Small Surface Mount Package (SOP8)
- 3) Pb-free plating; RoHS compliant
- 4) Halogen Free

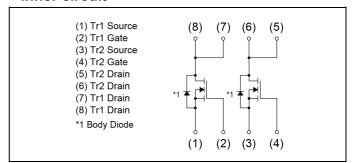
# Application

Switching

## Outline



## •Inner circuit



# Packaging specifications

	Packing	Embossed Tape
	Reel size (mm)	330
Туре	Tape width (mm)	12
	Quantity (pcs)	2500
	Taping code	TB1
	Marking	SH8KC7

# ● **Absolute maximum ratings** (T<sub>a</sub> = 25°C ,unless otherwise specified) < Tr1 and Tr2>

Parameter	Symbol	Value	Unit
Drain - Source voltage	V <sub>DSS</sub>	60	V
Continuous drain current	I <sub>D</sub>	±10.5	Α
Pulsed drain current	I <sub>DP</sub> *1	±42	Α
Gate - Source voltage	$V_{GSS}$	±20	V
Avalanche current, single pulse	I <sub>AS</sub> *2	10.5	Α
Avalanche energy, single pulse	E <sub>AS</sub> *2	8.7	mJ
Douge discipation (total)	P <sub>D</sub> *3	2.0	١٨/
Power dissipation (total)	P <sub>D</sub> *4	1.4	W
Junction temperature	T <sub>j</sub>	150	°C
Operating junction and storage temperature range	T <sub>stg</sub>	-55 to +150	°C

## Thermal resistance

Doromotor	Cymbol	Values			l leit
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal registeres innetion, embient (total)	$R_{thJA}^{*3}$	-	-	62.5	°C/W
Thermal resistance, junction - ambient (total)	R <sub>thJA</sub> *4	-	-	89.2	C/VV

# ● Electrical characteristics (T<sub>a</sub> = 25°C) < Tr1 and Tr2>

D .		0 177	Values			11.20	
Parameter	Symbol	Conditions	Min.	Min. Typ. Max.		Unit	
Drain - Source breakdown voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0V$ , $I_D = 1mA$	60	-	-	V	
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_{j}}$	I <sub>D</sub> = 1mA referenced to 25°C	-	38.9	-	mV/°C	
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 60V, V <sub>GS</sub> = 0V	-	-	1	μA	
Gate - Source leakage current	I <sub>GSS</sub>	$V_{GS} = \pm 20V, V_{DS} = 0V$	-	-	±100	nA	
Gate threshold voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}$ , $I_D = 1mA$	1.0	-	2.5	V	
Gate threshold voltage temperature coefficient	$\frac{\DeltaV_{GS(th)}}{\DeltaT_j}$	I <sub>D</sub> = 1mA referenced to 25°C	-	-4.7	-	mV/°C	
Static drain - source	D *5	V <sub>GS</sub> = 10V, I <sub>D</sub> = 10.5A	-	9.5	12.4	0	
on - state resistance	R <sub>DS(on)</sub> *5	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 10.5A	-	12.3	17.2	mΩ	
Gate resistance	$R_G$	-	-	0.9	-	Ω	
Forward Transfer Admittance	Y <sub>fs</sub>  *5	V <sub>DS</sub> = 5V, I <sub>D</sub> = 10.5A	10	-	-	S	

<sup>\*1</sup> Pw ≤ 10µs, Duty cycle ≤ 1%

<sup>\*2</sup> L  $\simeq$  0.1mH, V<sub>DD</sub> = 30V, R<sub>G</sub> = 25 $\Omega$ , Starting T<sub>j</sub> = 25 $^{\circ}$ C Fig.3-1,3-2

<sup>\*3</sup> Mounted on a ceramic board (30×30×0.8mm)

<sup>\*4</sup> Mounted on a Cu board (40×40×0.8mm)

<sup>\*5</sup> Pulsed

# ● Electrical characteristics (T<sub>a</sub> = 25°C) < Tr1 and Tr2>

Parameter	Cymahal	Conditions		Unit			
Parameter	Symbol Conditions —		Min.	Тур.	Max.	Offic	
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	1400	-	_	
Output capacitance C <sub>oss</sub>		V <sub>DS</sub> = 30V	-	350	-	pF	
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	-	26	-		
Turn - on delay time	t <sub>d(on)</sub> *5	V <sub>DD</sub> ≈ 30V,V <sub>GS</sub> = 10V	-	15.0	-		
Rise time	<b>t</b> <sub>r</sub> *5	I <sub>D</sub> = 5.25A	-	8.5	-		
Turn - off delay time	t <sub>d(off)</sub> *5	$R_L = 5.71\Omega$	-	43.0	-	ns	
Fall time	<b>t</b> <sub>f</sub> *5	$R_G = 10\Omega$	-	11.0	-		

# ● Gate charge characteristics (T<sub>a</sub> = 25°C) < Tr1 and Tr2>

Darameter	Cumbal	Conditions -		Values			Lloit	
Parameter	Symbol			Min.	Тур.	Max.	Unit	
Total mate about	O *5	V <sub>GS</sub> =	V <sub>GS</sub> = 10V	-	22.0	-		
Total gate charge	$Q_g^{*5}$		V <sub>DD</sub> ≈ 30V		-	10.8	-	<b>"</b> C
Gate - Source charge	Q <sub>gs</sub> *5	I <sub>D</sub> = 10.5A	V <sub>GS</sub> = 4.5V	-	3.5	-	nC	
Gate - Drain charge	Q <sub>gd</sub> *5			-	3.5	-		

# ● Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

## <Tr1 and Tr2>

Parameter	Symbol	Conditions		Unit			
Farameter	Symbol	ol Conditions -		Тур.	Max.	Offic	
Continuous forward current	I <sub>S</sub>	T <sub>a</sub> = 25°C	-	1	1.67	^	
Pulse forward current	I <sub>SP</sub> *1	1 <sub>a</sub> – 25 C	-	-	42	A	
Forward voltage	V <sub>SD</sub> *5	V <sub>GS</sub> = 0V, I <sub>S</sub> = 1.67A	-	-	1.2	V	
Reverse recovery time	t <sub>rr</sub> *5	I <sub>S</sub> = 10.5A, V <sub>GS</sub> = 0V	-	35	-	ns	
Reverse recovery charge	Q <sub>rr</sub> *5	di/dt = 100A/μs	-	39	-	nC	

Fig.1 Power Dissipation Derating Curve

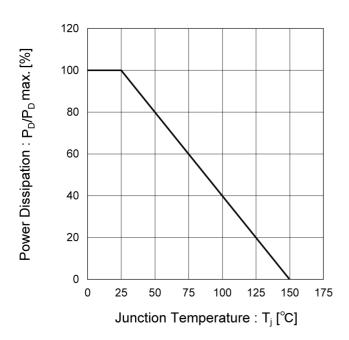
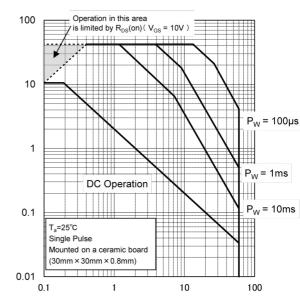


Fig.2 Maximum Safe Operating Area



Drain Current : I<sub>D</sub> [A]

Drain - Source Voltage : V<sub>DS</sub> [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

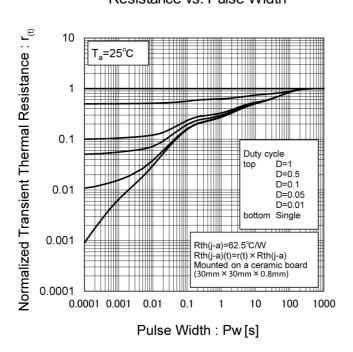


Fig.4 Single Pulse Maximum Power Dissipation

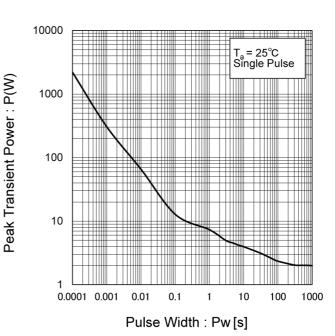


Fig.5 Typical Output Characteristics(I)

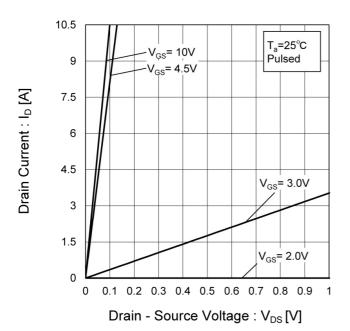
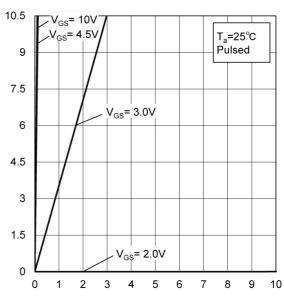


Fig.6 Typical Output Characteristics(II)



Drain Current : I<sub>D</sub> [A]

Drain - Source Voltage : V<sub>DS</sub> [V]

Fig.7 Breakdown Voltage vs.
Junction Temperature

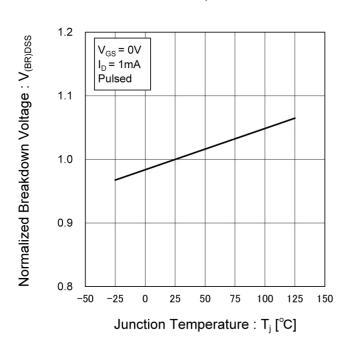


Fig.8 Typical Transfer Characteristics

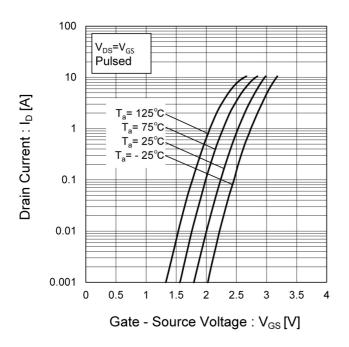


Fig.9 Gate Threshold Voltage vs.
Junction Temperature

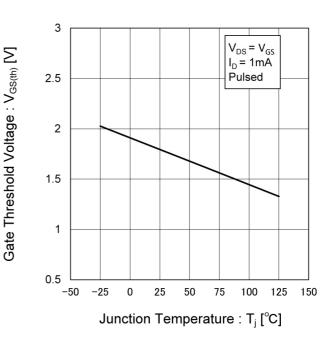


Fig.10 Forward Transfer Admittance vs.
Drain Current

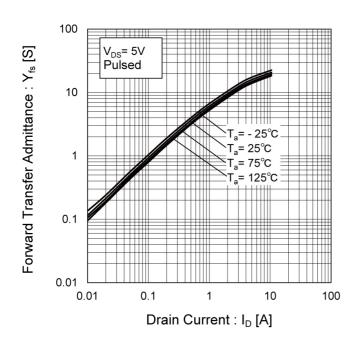


Fig.11 Drain Current Derating Curve

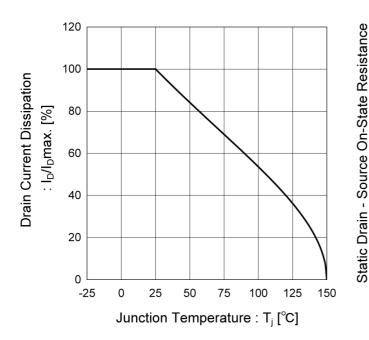


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

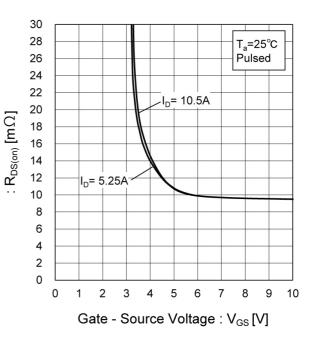


Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature

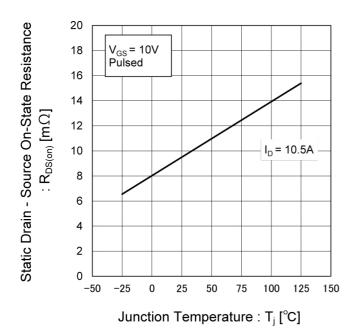


Fig.14 Static Drain - Source On - State Resistance vs. Drain Current (I)

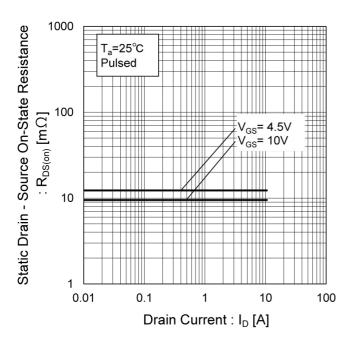


Fig.15 Static Drain - Source On - State Resistance vs. Drain Current (II)

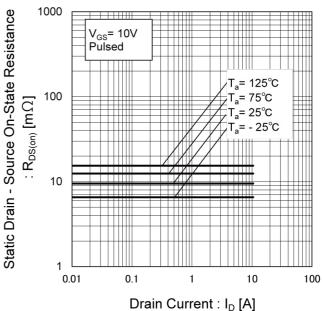


Fig.16 Static Drain - Source On - State Resistance vs. Drain Current (III)

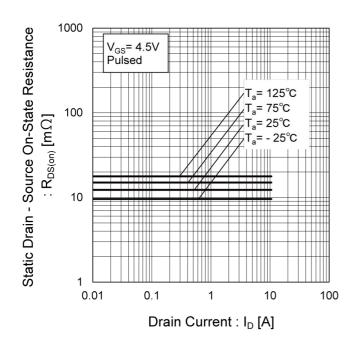


Fig.17 Typical Capacitances vs.

Drain - Source Voltage

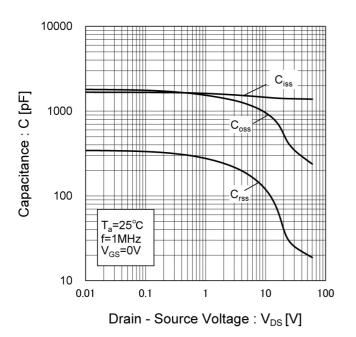


Fig.18 Switching Characteristics

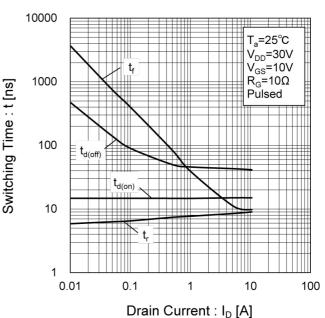


Fig.19 Typical Gate Charge

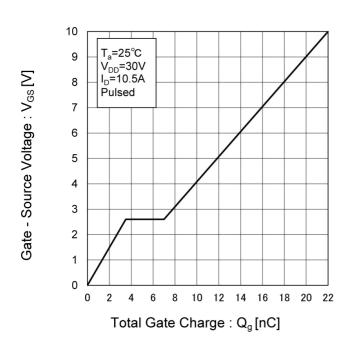
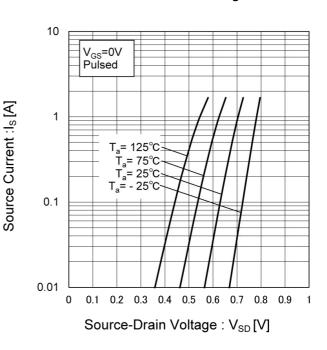


Fig.20 Source Current vs.
Source Drain Voltage



## • Measurement circuits < It is the same for the Tr1 and Tr2>

Fig.1-1 Switching Time Measurement Circuit

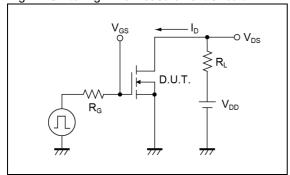


Fig.2-1 Gate Charge Measurement Circuit

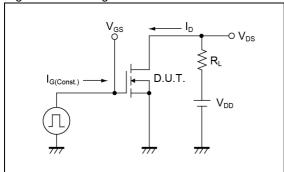


Fig.3-1 Avalanche Measurement Circuit

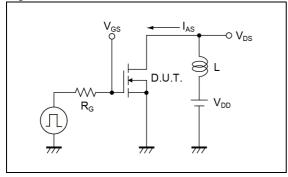


Fig.1-2 Switching Waveforms

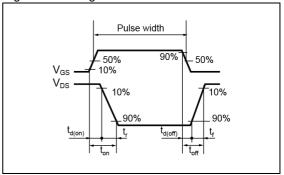


Fig.2-2 Gate Charge Waveform

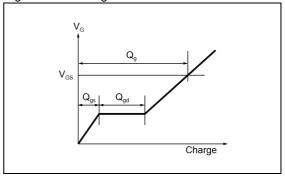
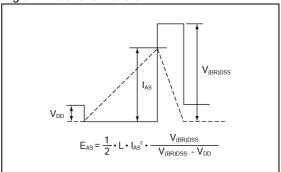


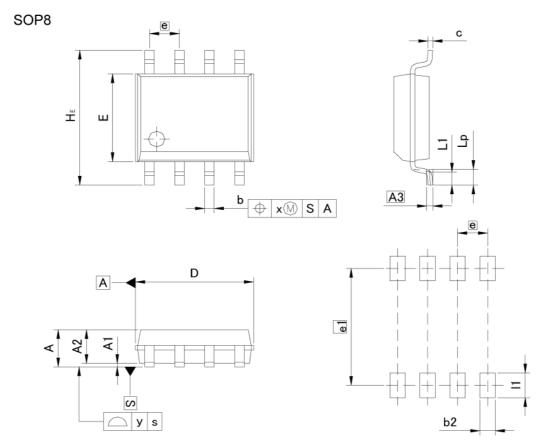
Fig.3-2 Avalanche Waveform



## Notice

This product might cause chip aging and breakdown under the large electrified environment. Please consider to design ESD protection circuit.

## Dimensions



Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIM	ETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
Α	-	1.75	-	0.069	
A1	0.	15	0.0	006	
A2	1.40	1.60	0.055	0.063	
A3	0.	25	0.0	010	
b	0.30	0.50	0.012	0.020	
С	0.10	0.30	0.004	0.012	
D	4.80	5.20	0.189	0.205	
Е	3.75	4.05	0.148	0.159	
е	1,	27	0.050		
HE	5.70	6.30	0.224	0.248	
L1	0.40	0.60	0.016	0.024	
Lp	0.65	0.85	0.026	0.033	
х	0.	15	0.006		
У	0.10		0.004		
DIM	MILIM	ETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	

0.65

1.15

5.15

Dimension in mm/inches

b2

e 1 11



0.026

0.045

0.203

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JÁPAN	USA	EU	CHINA
CLASSⅢ	ОГАССШ	CLASS II b	CL ACCIII
CLASSIV	CLASSⅢ	CLASSⅢ	CLASSⅢ

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  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

#### Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
  may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
  exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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